

## N-Channel Trench Power MOSFET

### General Description

The HD40N04 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

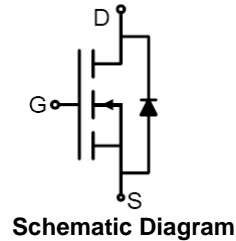
### Features

- $V_{DS} = 40V, I_D = 40A$   
 $R_{DS(ON)} < 15 \text{ m}\Omega @ V_{GS} = 10V$   
 $R_{DS(ON)} < 21 \text{ m}\Omega @ V_{GS} = 4.5V$
- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

### Application

- PWM applications
- Load switch
- Power management

**100% UIS TESTED!**  
**100%  $\Delta V_{ds}$  TESTED!**



### Package Marking and Ordering Information

| Device Marking | Device  | Device Package | Reel Size | Tape width | Quantity |
|----------------|---------|----------------|-----------|------------|----------|
| HD40N04        | HD40N04 | TO-252         | 325mm     | 16mm       | 2500     |

**Table 1. Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ )**

| Symbol           | Parameter  | Value      | Unit             |
|------------------|--|------------|------------------|
| $V_{DS}$         | Drain-Source Voltage ( $V_{GS}=0V$ )                 | 40         | V                |
| $V_{GS}$         | Gate-Source Voltage ( $V_{DS}=0V$ )                  | $\pm 20$   | V                |
| $I_D$            | Drain Current-Continuous( $T_C=25^\circ\text{C}$ )   | 40         | A                |
|                  | Drain Current-Continuous( $T_C=100^\circ\text{C}$ )  | 28         | A                |
| $I_{DM (pluse)}$ | Drain Current-Continuous@ Current-Pulsed (Note 1)    | 160        | A                |
| $P_D$            | Maximum Power Dissipation( $T_C=25^\circ\text{C}$ )  | 50         | W                |
|                  | Maximum Power Dissipation( $T_C=100^\circ\text{C}$ ) | 25         |                  |
| $E_{AS}$         | Avalanche energy (Note 2)                            | 90         | mJ               |
| $T_J, T_{STG}$   | Operating Junction and Storage Temperature Range     | -55 To 175 | $^\circ\text{C}$ |

**Table 2. Thermal Characteristic**

| Symbol          | Parameter                            | Typ | Max | Unit               |
|-----------------|--------------------------------------|-----|-----|--------------------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | -   | 3   | $^\circ\text{C/W}$ |

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

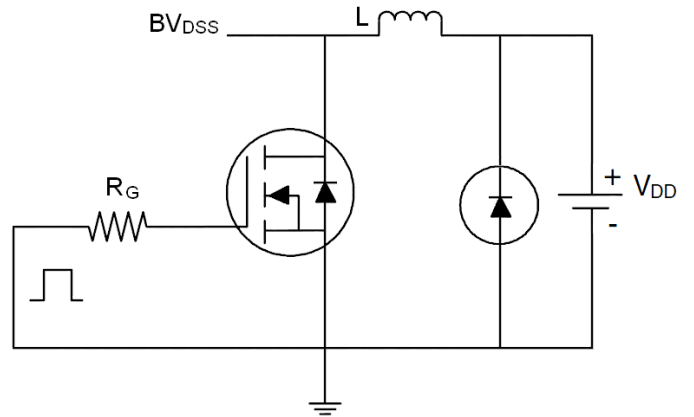
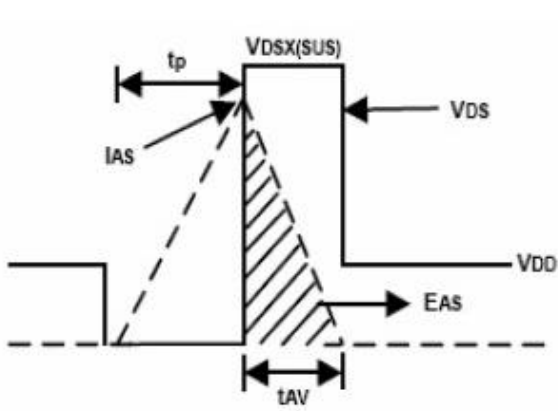
| Symbol                                    | Parameter                          | Conditions  | Min | Typ  | Max  | Unit |
|---|------------------------------------|---|-----|------|------|------|
| <b>On/Off States</b>                      |                                    |   |     |      |      |      |
| BV <sub>DSS</sub>                         | Drain-Source Breakdown Voltage     | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA  | 40  |      |      | V    |
| I <sub>DSS</sub>                          | Zero Gate Voltage Drain Current    | V <sub>DS</sub> =40V, V <sub>GS</sub> =0V   |     |      | 1    | μA   |
| I <sub>GSS</sub>                          | Gate-Body Leakage Current          | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V  |     |      | ±100 | nA   |
| V <sub>GS(th)</sub>                       | Gate Threshold Voltage             | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                                | 1   | 1.7  | 2.5  | V    |
| g <sub>FS</sub>                           | Forward Transconductance           | V <sub>DS</sub> =5V, I <sub>D</sub> =10A  |     | 21   |      | S    |
| R <sub>DS(ON)</sub>                       | Drain-Source On-State Resistance   | V <sub>GS</sub> =10V, I <sub>D</sub> =20A   |     | 10.5 | 15   | mΩ   |
|   |                                    | V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A  |     | 15   | 21   | mΩ   |
| <b>Dynamic Characteristics</b>            |                                    |   |     |      |      |      |
| C <sub>iss</sub>                          | Input Capacitance                  | V <sub>DS</sub> =25V, V <sub>GS</sub> =0V,<br>f=1.0MHz                                  |     | 944  |      | pF   |
| C <sub>oss</sub>                          | Output Capacitance                 |   |     | 83   |      | pF   |
| C <sub>rss</sub>                          | Reverse Transfer Capacitance       |   |     | 70   |      | pF   |
| R <sub>g</sub>                            | Gate resistance                    | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz                                      |     | 2.5  |      | Ω    |
| <b>Switching Times</b>                    |                                    |   |     |      |      |      |
| t <sub>d(on)</sub>                        | Turn-on Delay Time                 | V <sub>GS</sub> =10V, V <sub>DS</sub> =20V,<br>R <sub>L</sub> =1Ω, R <sub>GEN</sub> =3Ω |     | 5.5  |      | nS   |
| t <sub>r</sub>                            | Turn-on Rise Time                  |   |     | 12   |      | nS   |
| t <sub>d(off)</sub>                       | Turn-Off Delay Time                |   |     | 22   |      | nS   |
| t <sub>f</sub>                            | Turn-Off Fall Time                 |   |     | 6    |      | nS   |
| Q <sub>g</sub>                            | Total Gate Charge                  | V <sub>GS</sub> =10V, V <sub>DS</sub> =25V, I <sub>D</sub> =14A                         |     | 23.5 |      | nC   |
| Q <sub>gs</sub>                           | Gate-Source Charge                 |   |     | 2.1  |      | nC   |
| Q <sub>gd</sub>                           | Gate-Drain Charge                  |   |     | 8.9  |      | nC   |
| <b>Source-Drain Diode Characteristics</b> |                                    |   |     |      |      |      |
| I <sub>SD</sub>                           | Source-Drain Current(Body Diode)   |   |     |      | 40   | A    |
| V <sub>SD</sub>                           | Forward on Voltage                 | V <sub>GS</sub> =0V, I <sub>S</sub> =20A  |     |      | 1.2  | V    |
| t <sub>rr</sub>                           | Body Diode Reverse Recovery Time   | I <sub>F</sub> =20A, dI/dt=100A/μs  |     | 6    |      | ns   |
| Q <sub>rr</sub>                           | Body Diode Reverse Recovery Charge | I <sub>F</sub> =20A, dI/dt=100A/μs  |     | 4.2  |      | nC   |

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

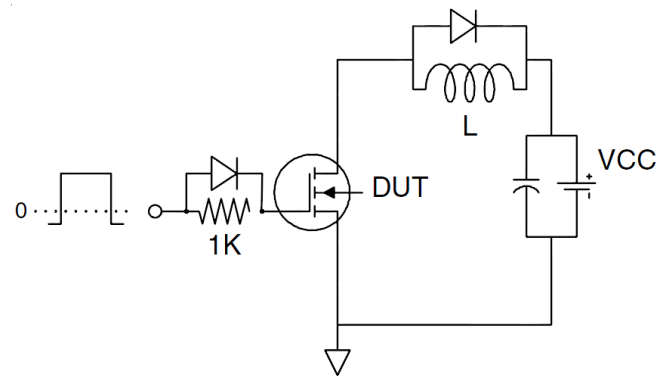
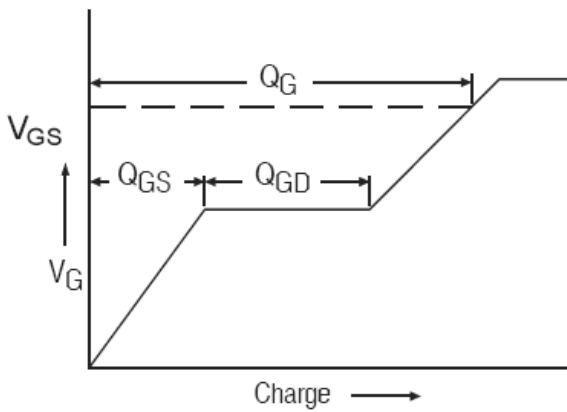
 Notes 2.EAS condition: T<sub>J</sub>=25°C, VDD=30V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω

## Test Circuit

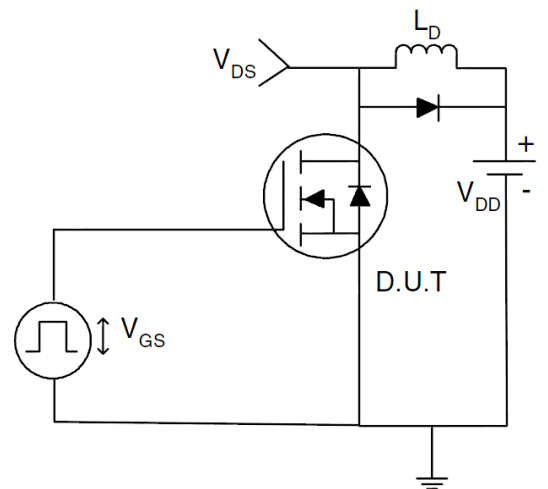
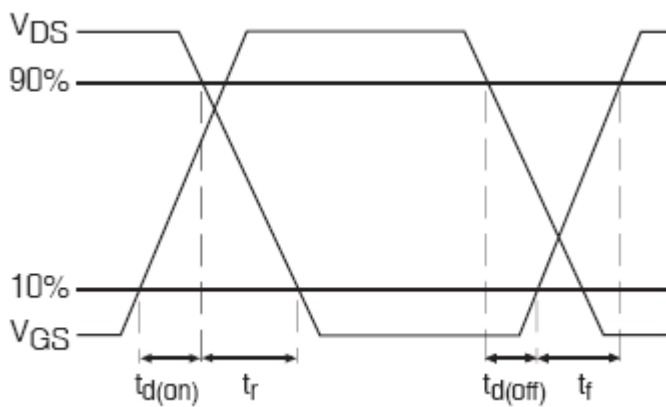
### 1) $E_{AS}$ Test Circuits



### 2) Gate Charge Test Circuit:



### 3) Switch Time Test Circuit:



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure 1. Output Characteristics

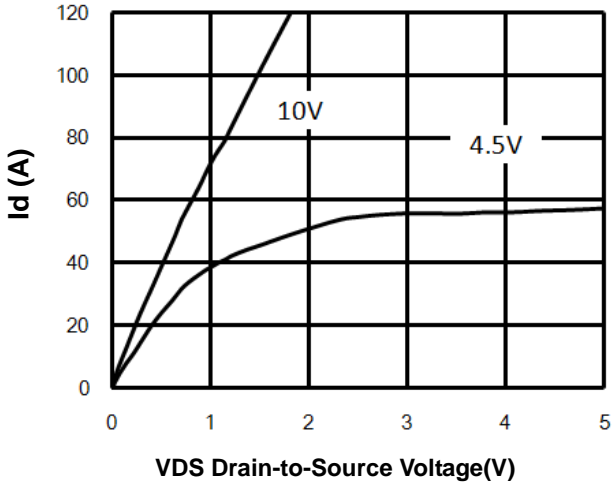


Figure 2. Transfer Characteristics

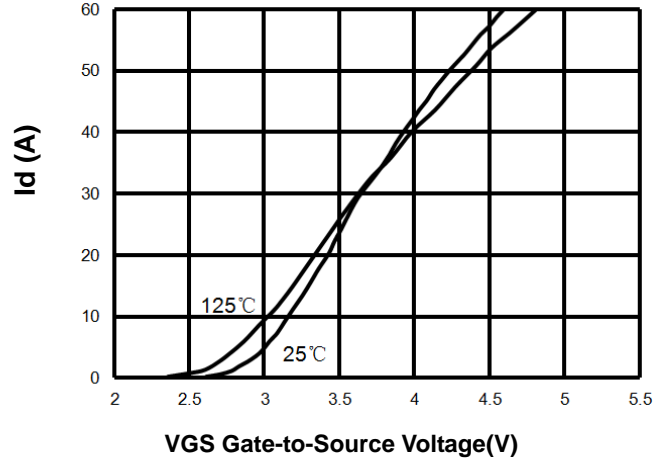


Figure 3. Max  $BV_{DSS}$  vs Junction Temperature

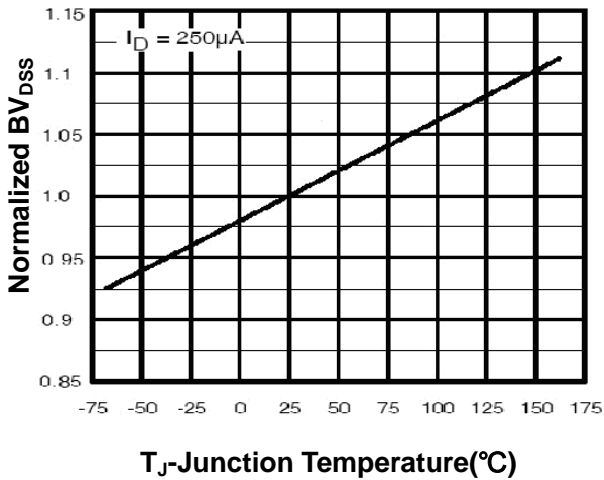


Figure 4. Drain Current

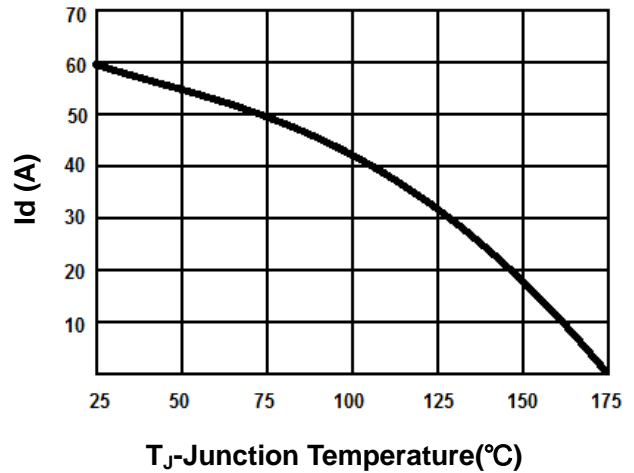


Figure 5.  $V_{GS(th)}$  vs Junction Temperature

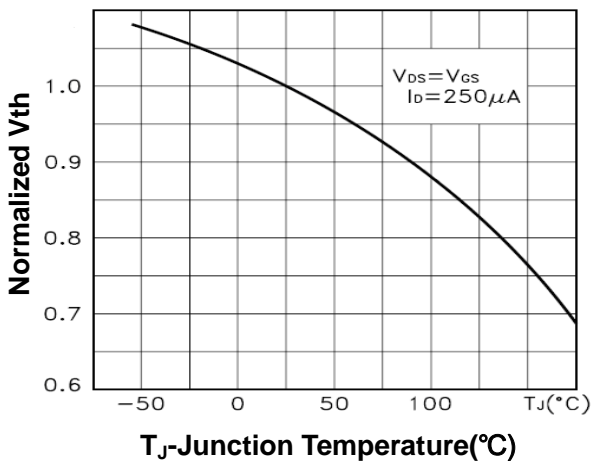


Figure 6.  $R_{DS(ON)}$  vs Junction Temperature

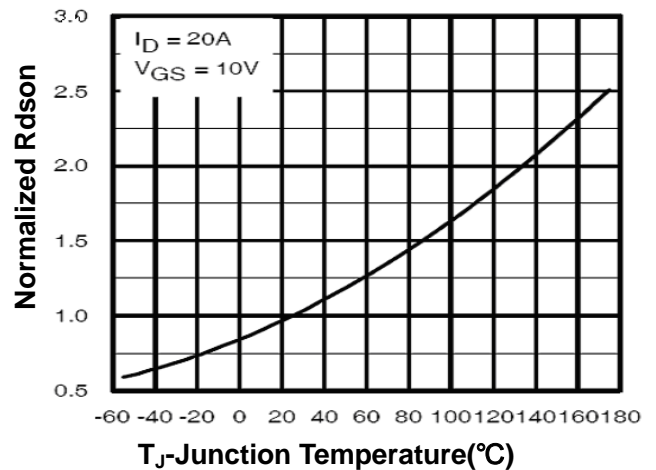


Figure 7. Gate Charge Waveforms

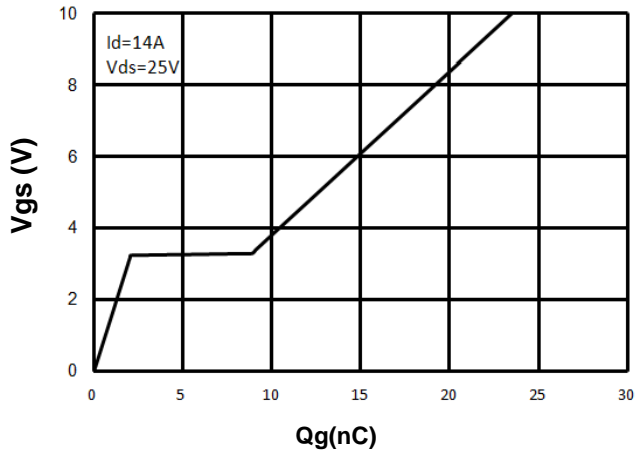


Figure 8. Capacitance

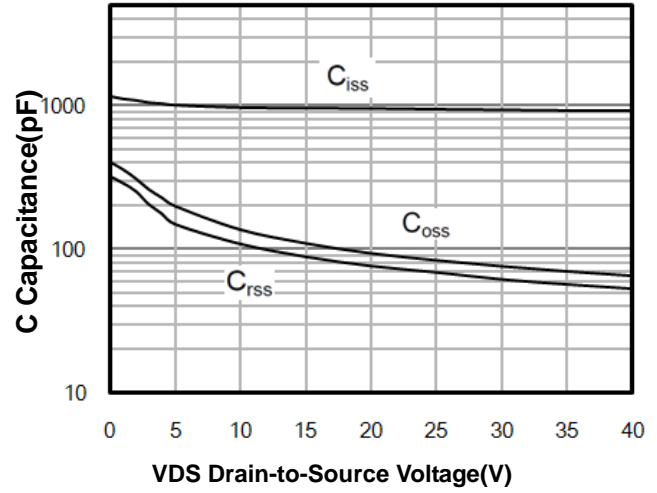


Figure 9. Body-Diode Characteristics

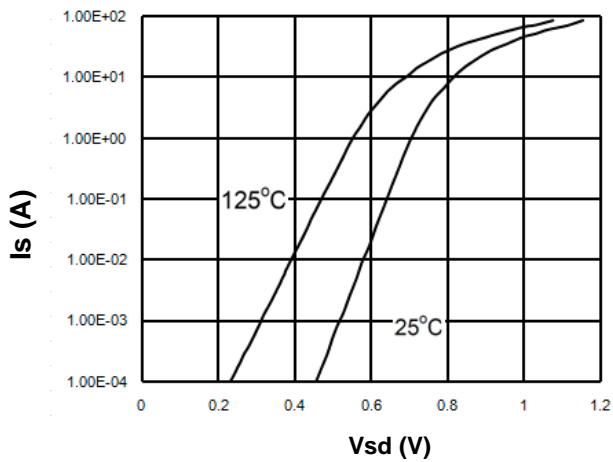
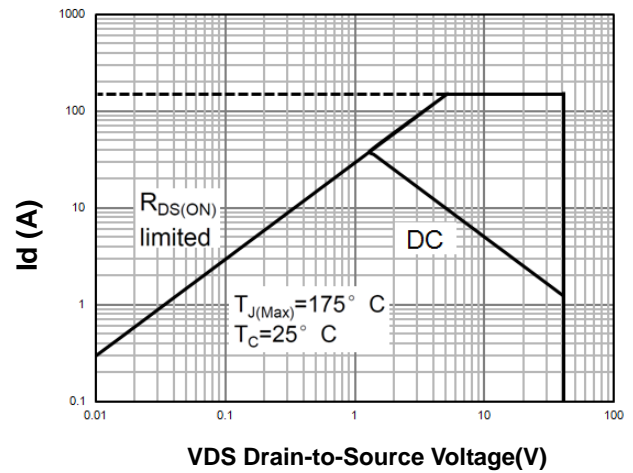
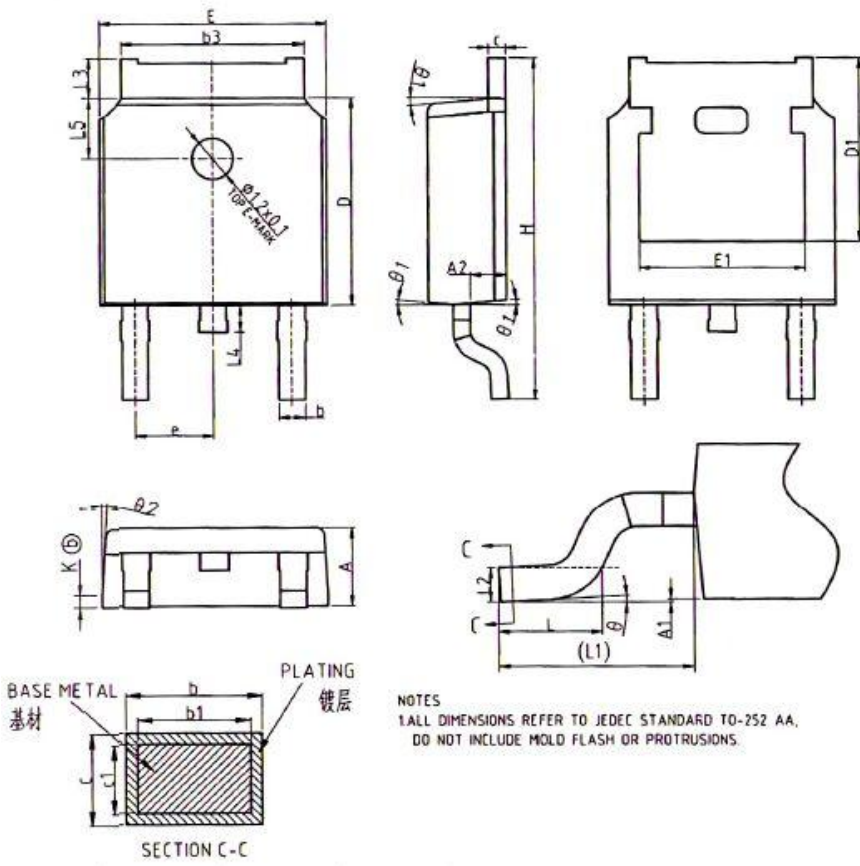


Figure 10. Maximum Safe Operating Area



## TO-252 Package Information



| COMMON DIMENSIONS |          |       |       |
|-------------------|----------|-------|-------|
| SYMBOL            | mm       |       |       |
|                   | MIN      | NOM   | MAX   |
| A                 | 2.20     | 2.30  | 2.38  |
| A1                | 0.00     | -     | 0.10  |
| A2                | 0.97     | 1.07  | 1.17  |
| b                 | 0.72     | 0.78  | 0.85  |
| b1                | 0.71     | 0.76  | 0.81  |
| b3                | 5.23     | 5.33  | 5.46  |
| c                 | 0.47     | 0.53  | 0.58  |
| c1                | 0.46     | 0.51  | 0.56  |
| D                 | 6.00     | 6.10  | 6.20  |
| D1                | 5.30REF  |       |       |
| E                 | 6.50     | 6.60  | 6.70  |
| E1                | 4.70     | 4.83  | 4.92  |
| e                 | 2.286BSC |       |       |
| H                 | 9.90     | 10.10 | 10.30 |
| L                 | 1.40     | 1.50  | 1.70  |
| L1                | 2.90REF  |       |       |
| L2                | 0.51BSC  |       |       |
| L3                | 0.90     | -     | 1.25  |
| L4                | 0.60     | 0.80  | 1.00  |
| L5                | 1.70     | 1.80  | 1.90  |
| $\theta$          | 0°       | -     | 8°    |
| $\theta 1$        | 5°       | 7°    | 9°    |
| $\theta 2$        | 5°       | 7°    | 9°    |
| K                 | 0.10REF  |       |       |

NOTES  
1. ALL DIMENSIONS REFER TO JEDEC STANDARD TO-252 AA.  
DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.